PRODUCT DATA SHEET

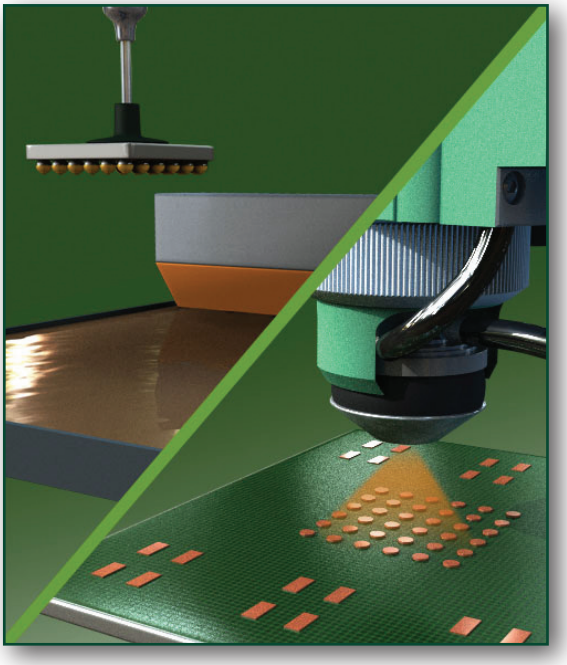
Flip-Chip Flux NC-26-A

Features

- Designed for flip-chip dipping applications
- Tackiness suitable for holding die during assembly
- Bubble-free airless packaging
- Ultra-low residue
- Halogen-free
- No-clean

Introduction

Flip-Chip Flux NC-26-A is a halogen-free, no-clean flip-chip dipping flux which is designed to leave a completely benign, clear residue. The reduction in residue optimizes underfill adhesion and decreases possible outgassing during underfill cure.



Properties

Property	Value	Test Method
Flux Type	REL0	J-STD-004 (IPC-TM-650: 2.3.32 and 2.3.33)
Color	Light Tan	Visual
Typical Viscosity	4kcps	Brookfield DV-I. 51CPE Spindle @10rpm after 5 mins
Typical Tack Strength	200 g/cm^2	J-STD-005 (IPC-TM-650: 2.4.44)
Typical Acid Value	36mg KOH/g	Titration
SIR (ohms)	Pass	J-STD-004 (IPC-TM-650: 2.6.3.3 IPC-B-24)
Typical Post Reflow Residual Weight	~5%	TGA Data
Working Life	≥ 8 hr	Customer Experience (Dipping)
Shelf Life	6 months when stored at 0 to 30°C	Viscosity Change/ Microscope Examination

All information is for reference only. Not to be used as incoming product specifications.

Application

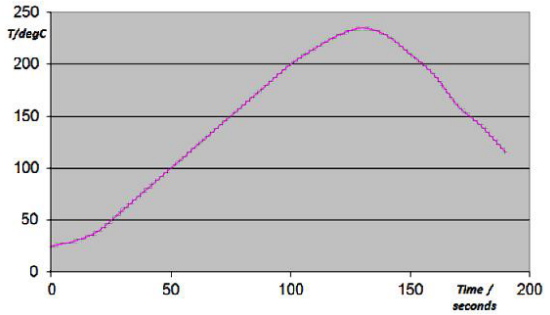
Flip-Chip Flux NC-26-A will have strong adhesion to epoxy-based underfill materials, especially epoxy-amine and epoxy-acid based chemistries. **Flip-Chip Flux NC-26-A** should also be suitable for use with many epoxy-anhydride systems.

Cleaning

Flip-Chip Flux NC-26-A is designed for no-clean applications. If necessary, the flux can be removed by using a commercially available flux cleaner. Please contact an Indium Corporation Technical Service Engineer for recommendations of cleaners to suit your process needs.

Reflow

Recommended Profile:



Flip-Chip Flux NC-26-A is intended to be used in a nitrogen reflow environment of 100ppm oxygen or less. Some applications can utilize this material in an air environment, although best results will be obtained in an inert atmosphere. **Flip-Chip Flux NC-26-A** can be used on many surface finishes including immersion Ag, Cu, and AuNi. These surfaces can be soldered with SnPb or Pb-free alloys, but require nitrogen if reflow temperatures exceed 240°C.

OVER→

Form No. 98835 (A4) R2

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Flip-Chip Flux NC-26-A

Packaging

Flip-Chip Flux NC-26-A is most commonly available in 10–30g syringes. Other packaging can be provided to meet specific requirements.

Storage

Flip-Chip Flux NC-26-A syringes and cartridges should be stored tip down for maximum shelf life. **Flip-Chip Flux NC-26-A** should be allowed to reach ambient temperature before use if stored cold.

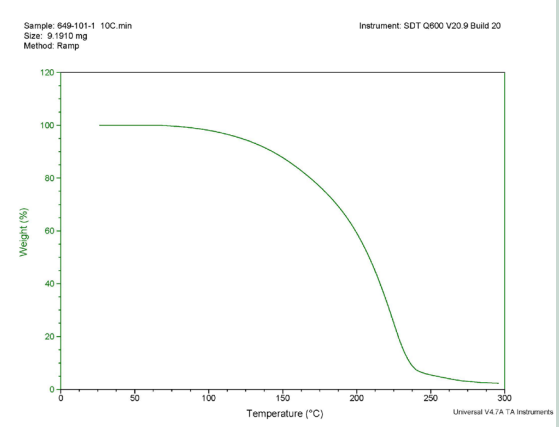
Technical Support

Indium Corporation sets the industry standard in providing rapid response, on-site technical support for our customers worldwide. Indium Corporation's team of Technical Support Engineers can provide expertise in all aspects of Materials Science and Semiconductor Packaging process applications.

Safety Data Sheets

The SDS for this product can be found online at http://www.indium.com/sds

Thermogravimetric Analysis (TGA)



TGA was performed at a ramp rate of 10°C per minute.

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